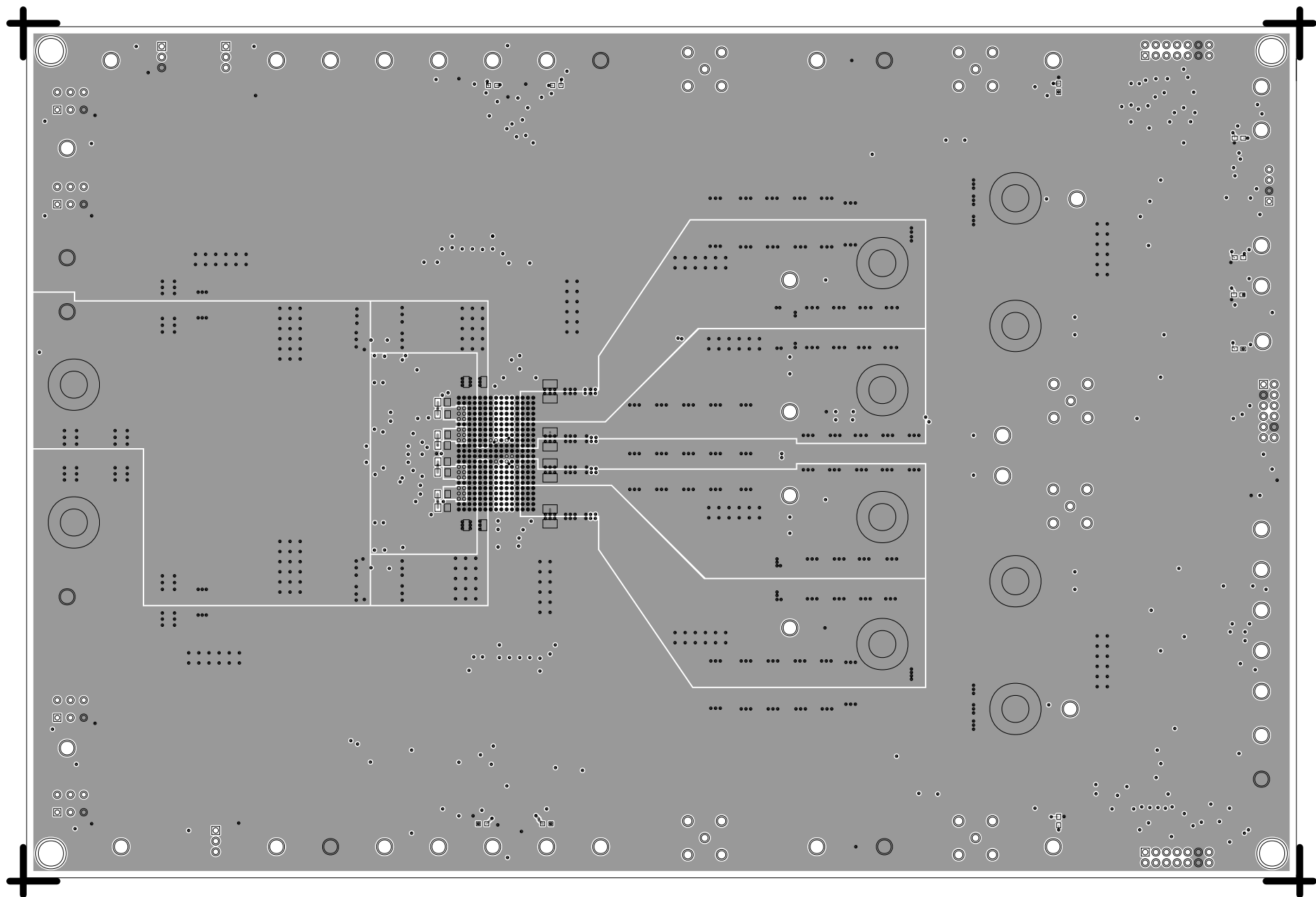


SECONDARY SIDE

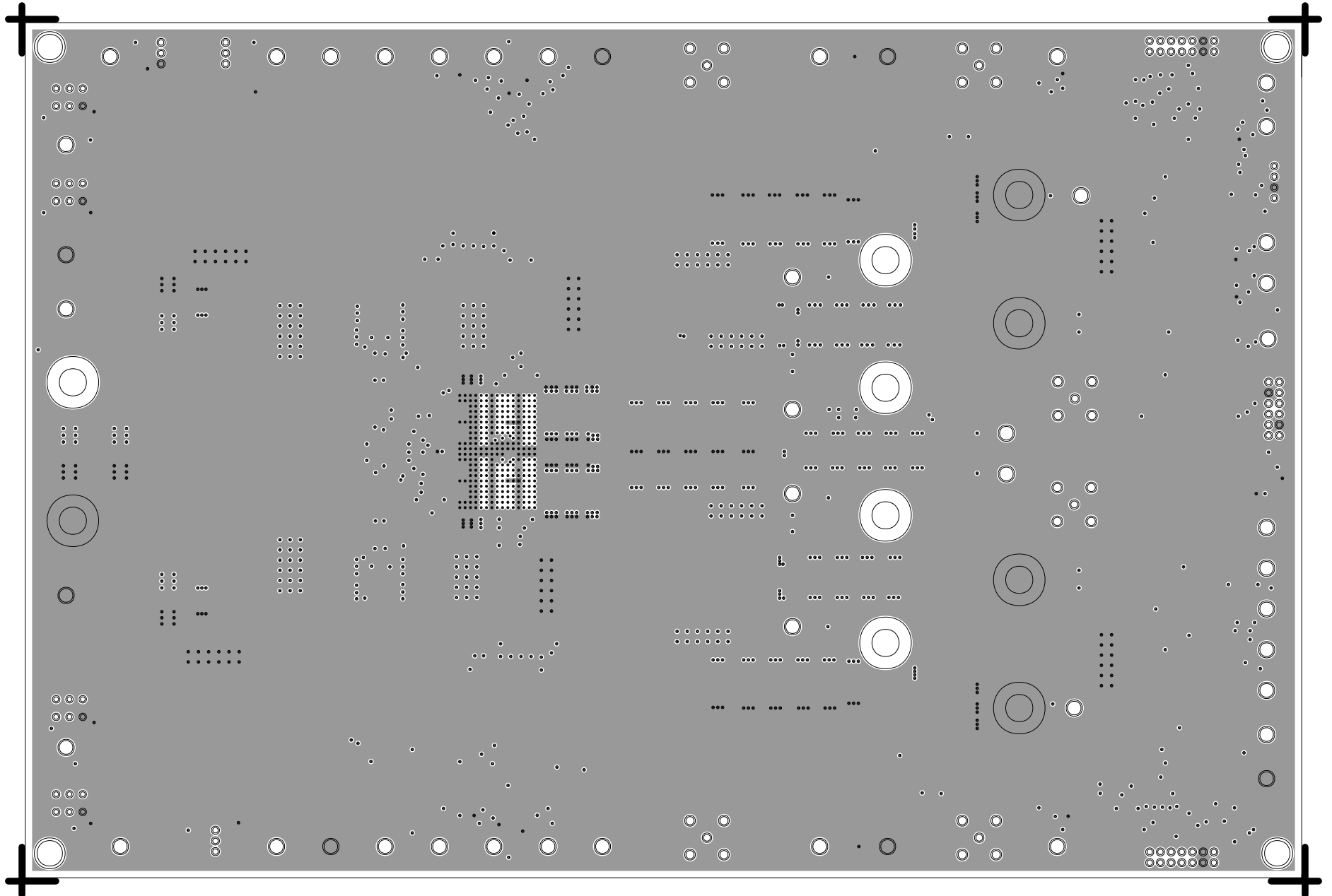
SIZE	FSCM NO	DRAWING NUMBER	REV
D	24355	01-070748	B
SCALE	1/1	SHEET 2 OF 2	

L1 PRIMARY
08-070748-01
REV B

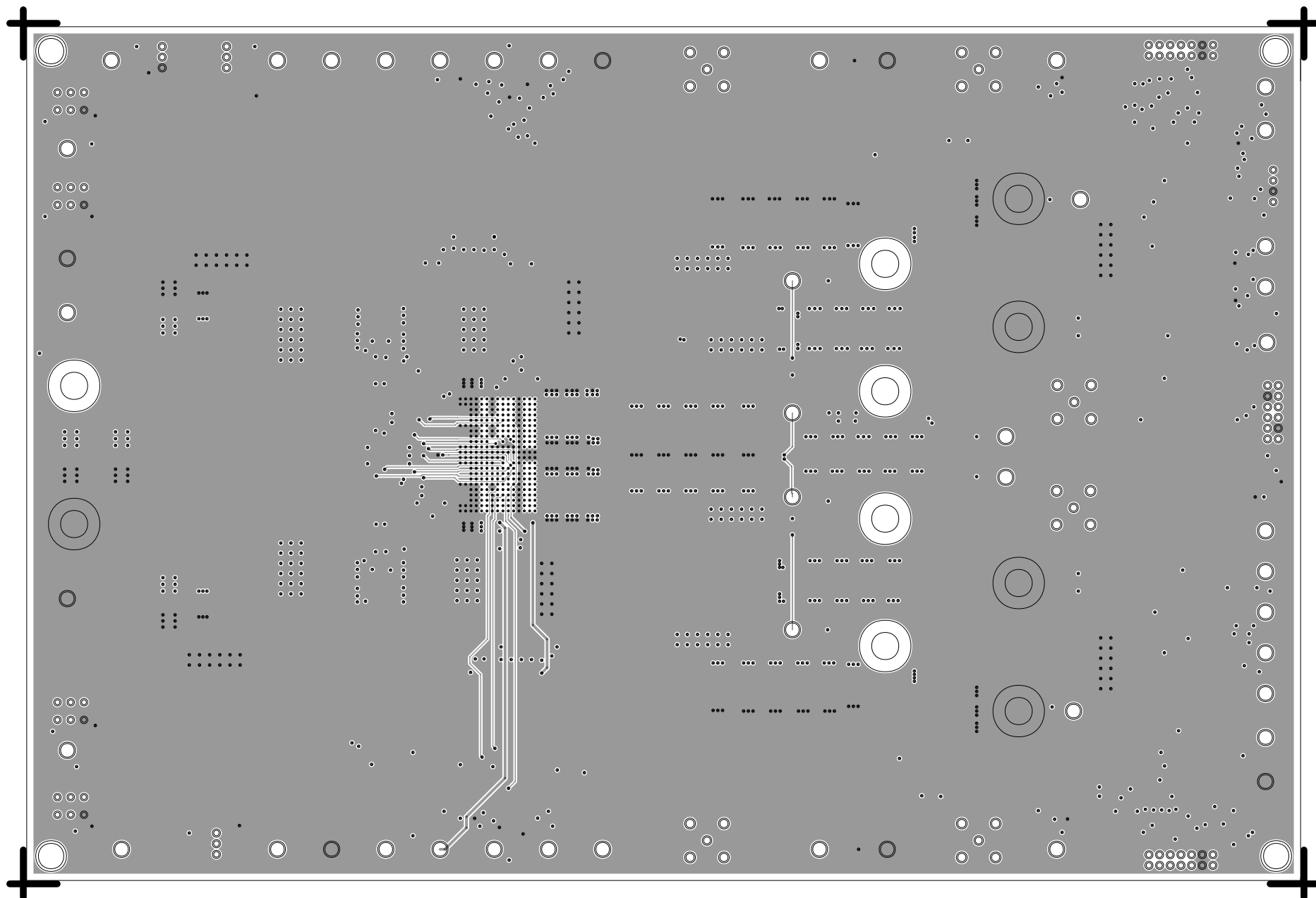


PRIMARY SIDE
08-707048 REV B

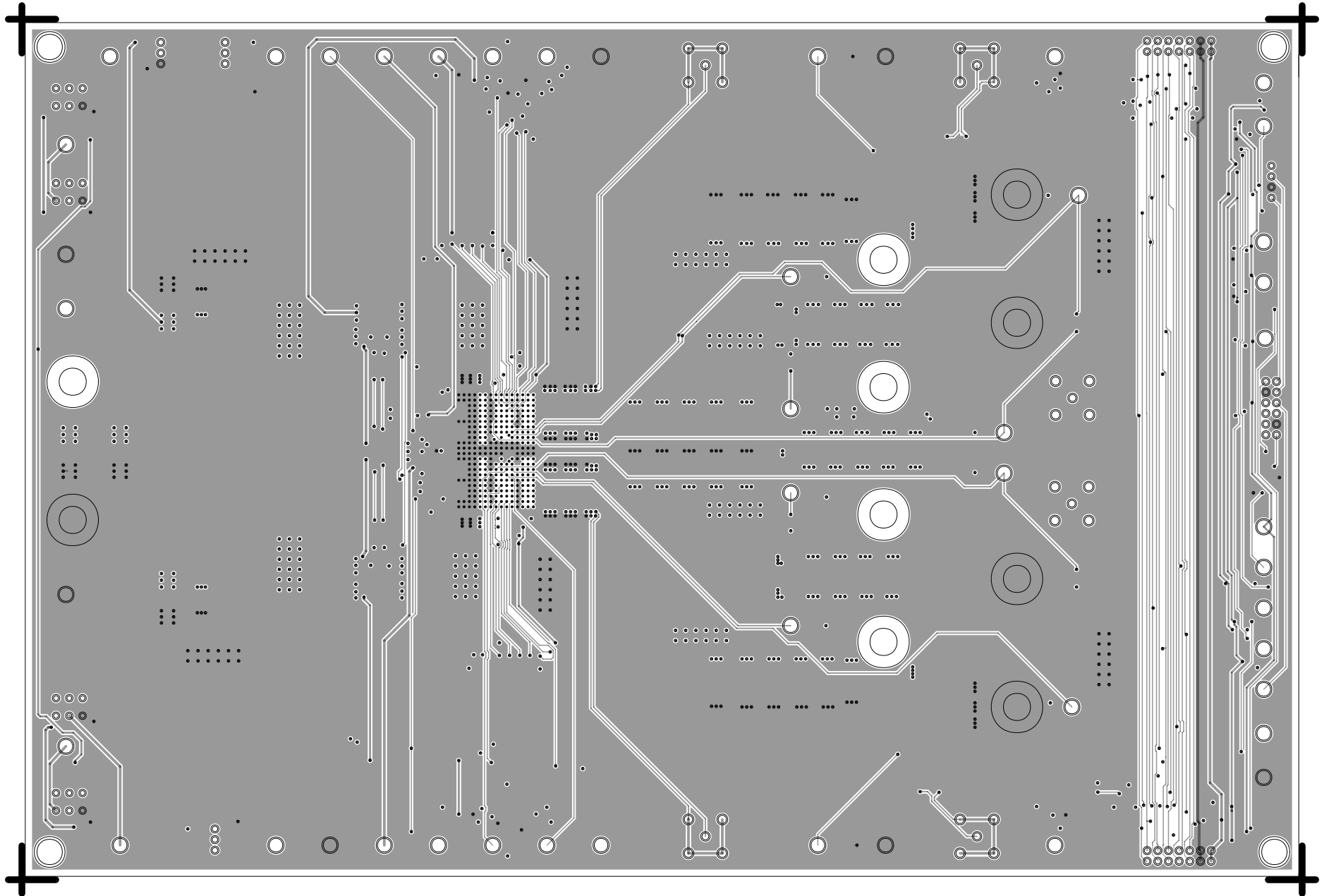
LAYER 2
08-070748-07
REV B



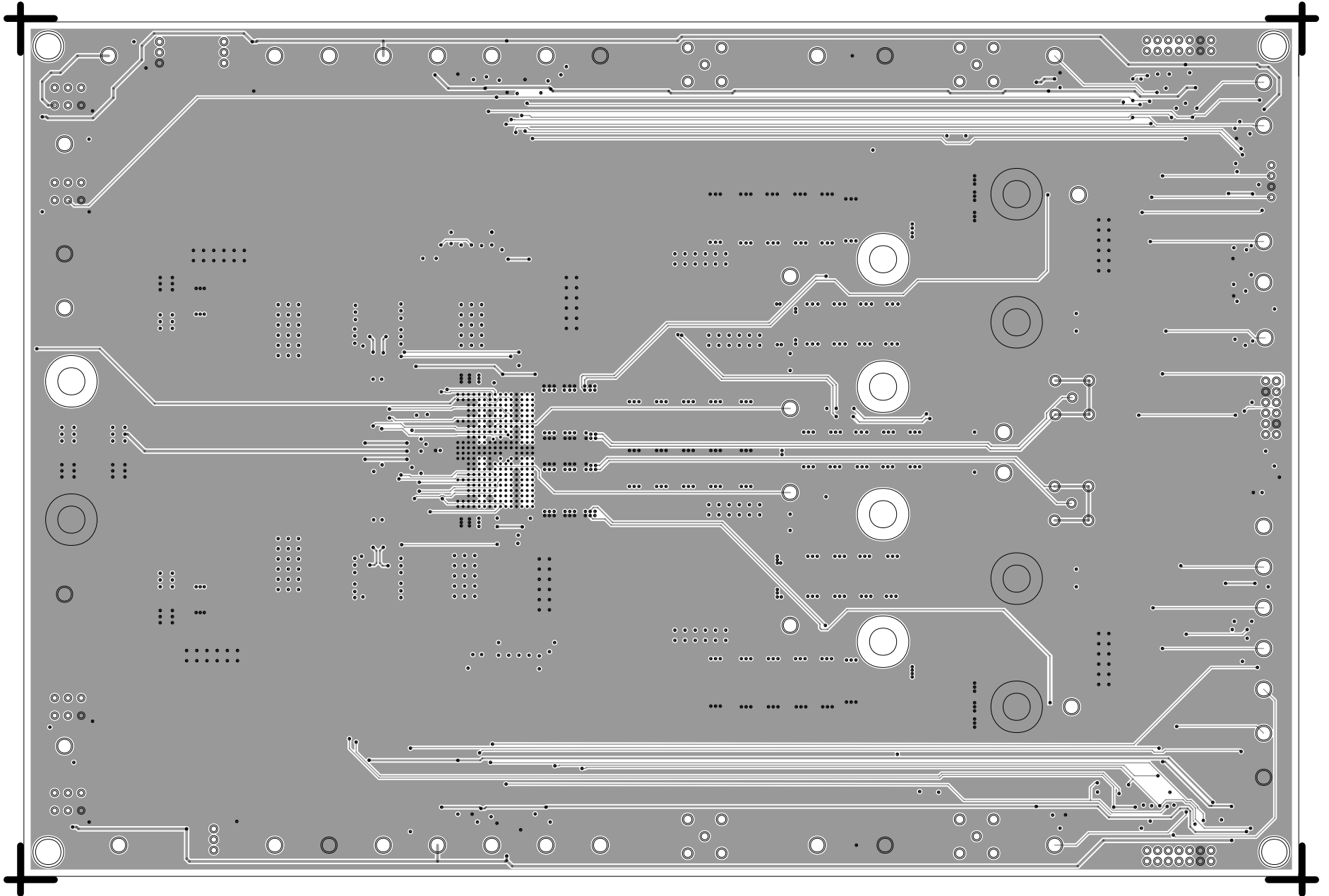
LAYER 3
08-070748-08
REV B



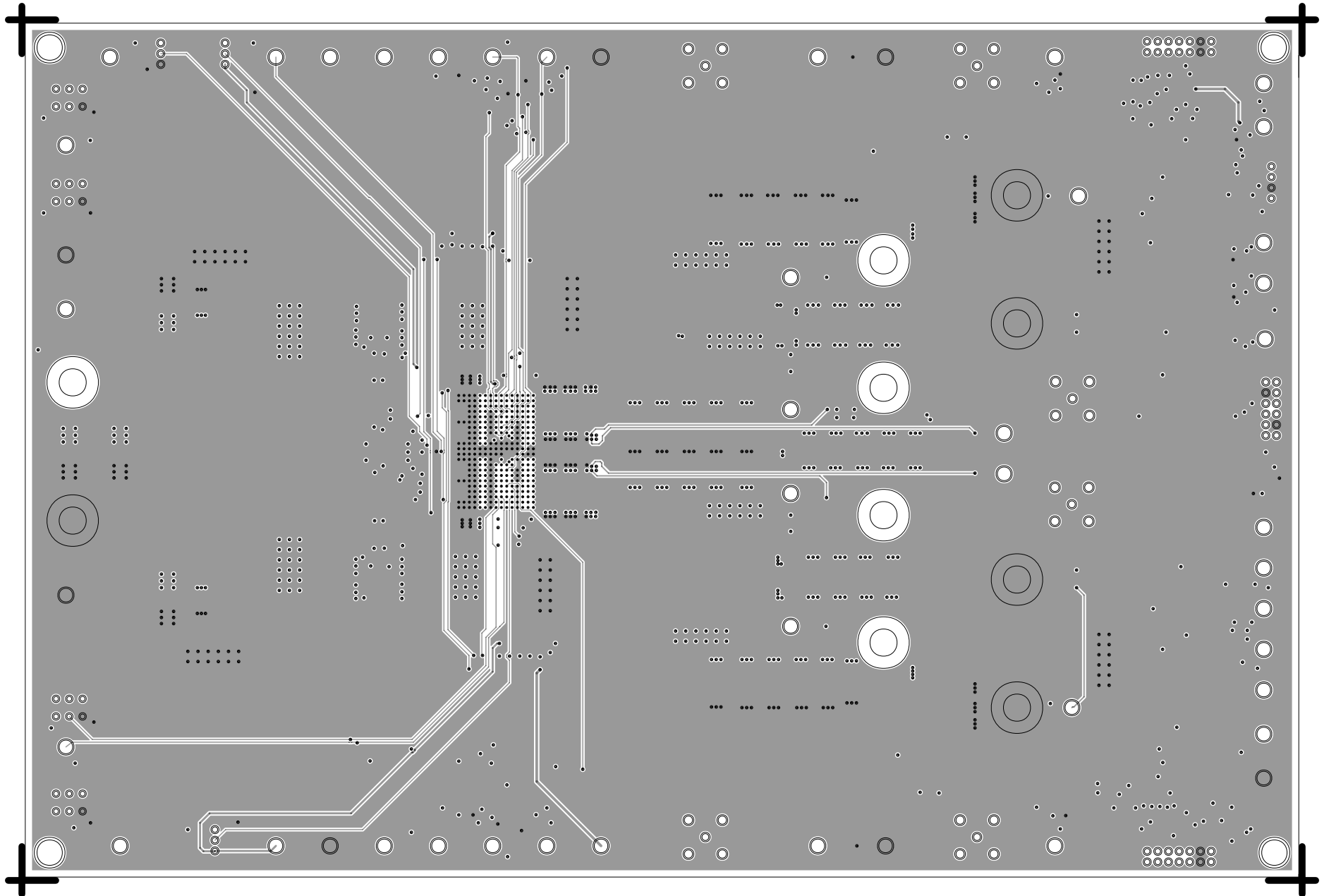
LAYER 4
08-070748-09
REV B



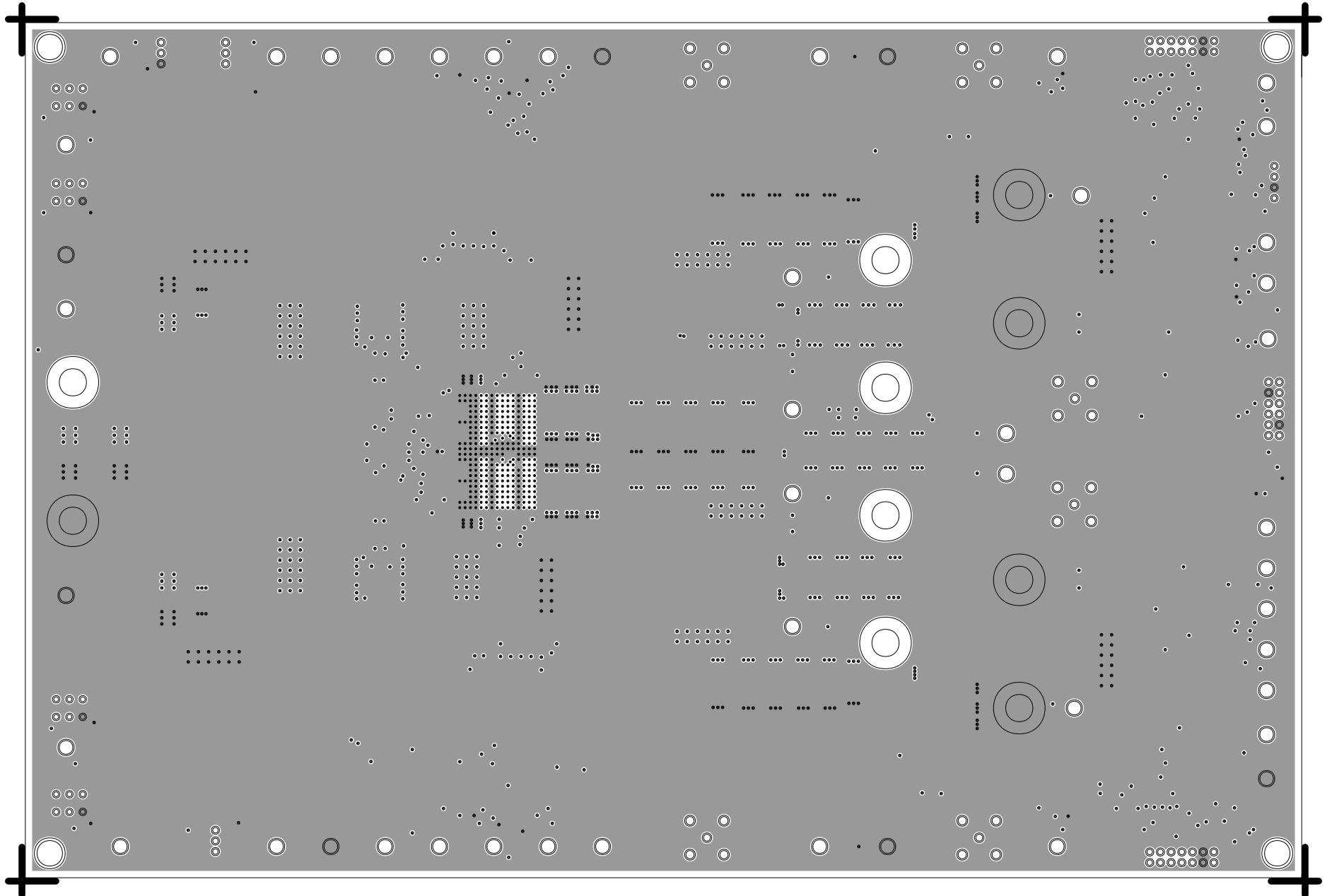
LAYER 5
08-070748-10
REV B



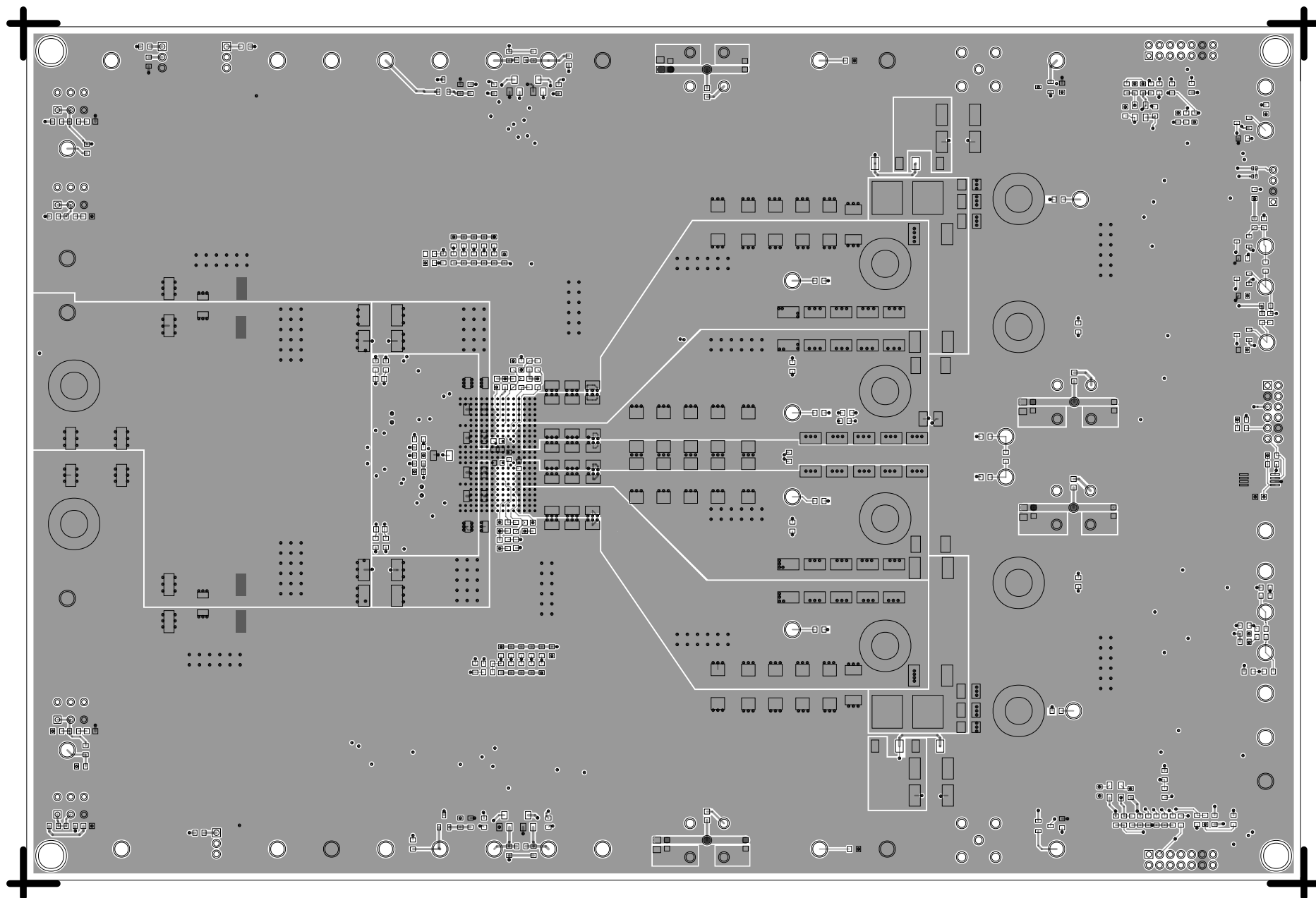
LAYER 6
08-070748-11
REV B



LAYER 7
08-070748-12
REV B



L08 SECONDARY
08-070748-02
REV B

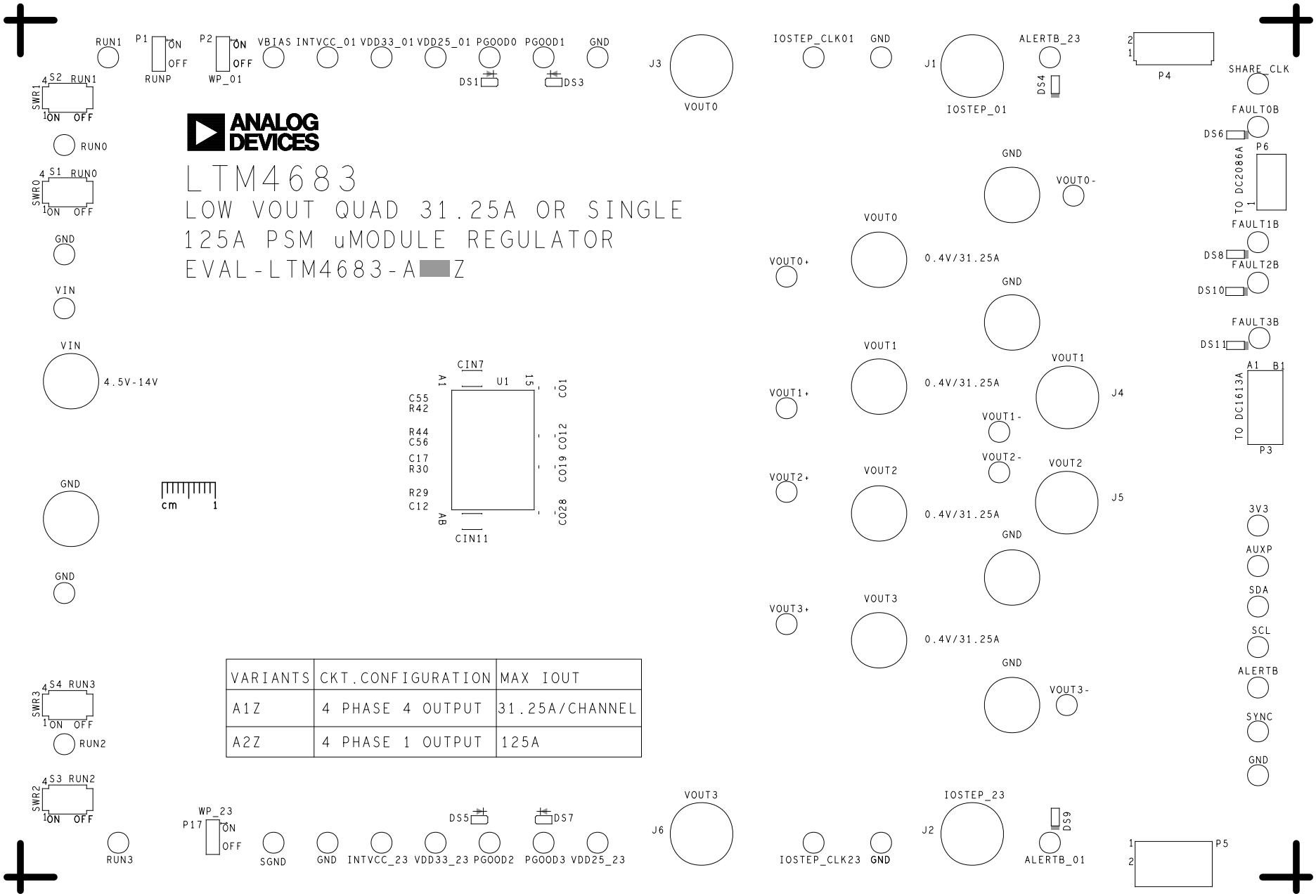


08-070748 REV B
SECONDARY 2IDE

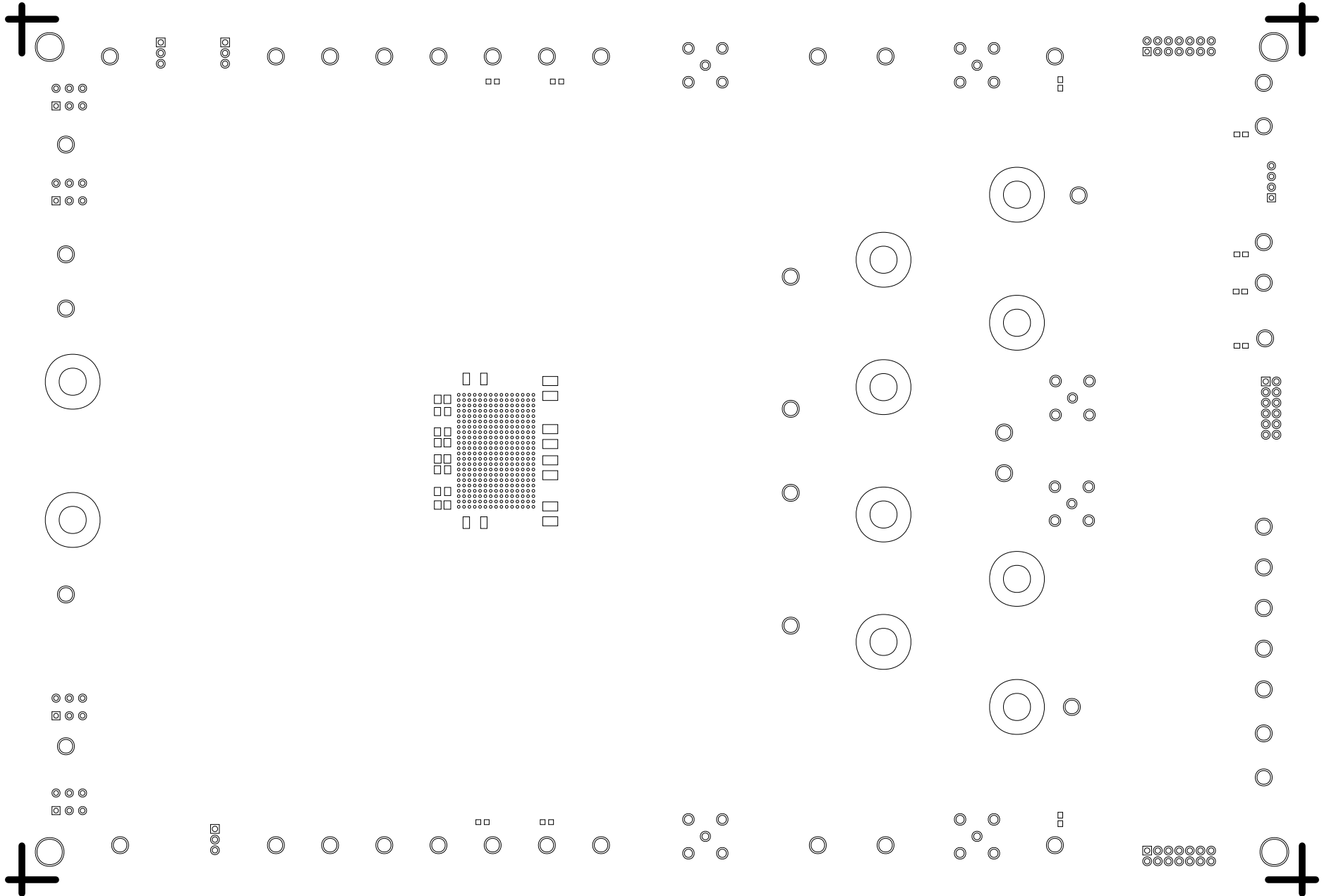
SILKSCREEN PRIMARY

08-070748-03

REV B



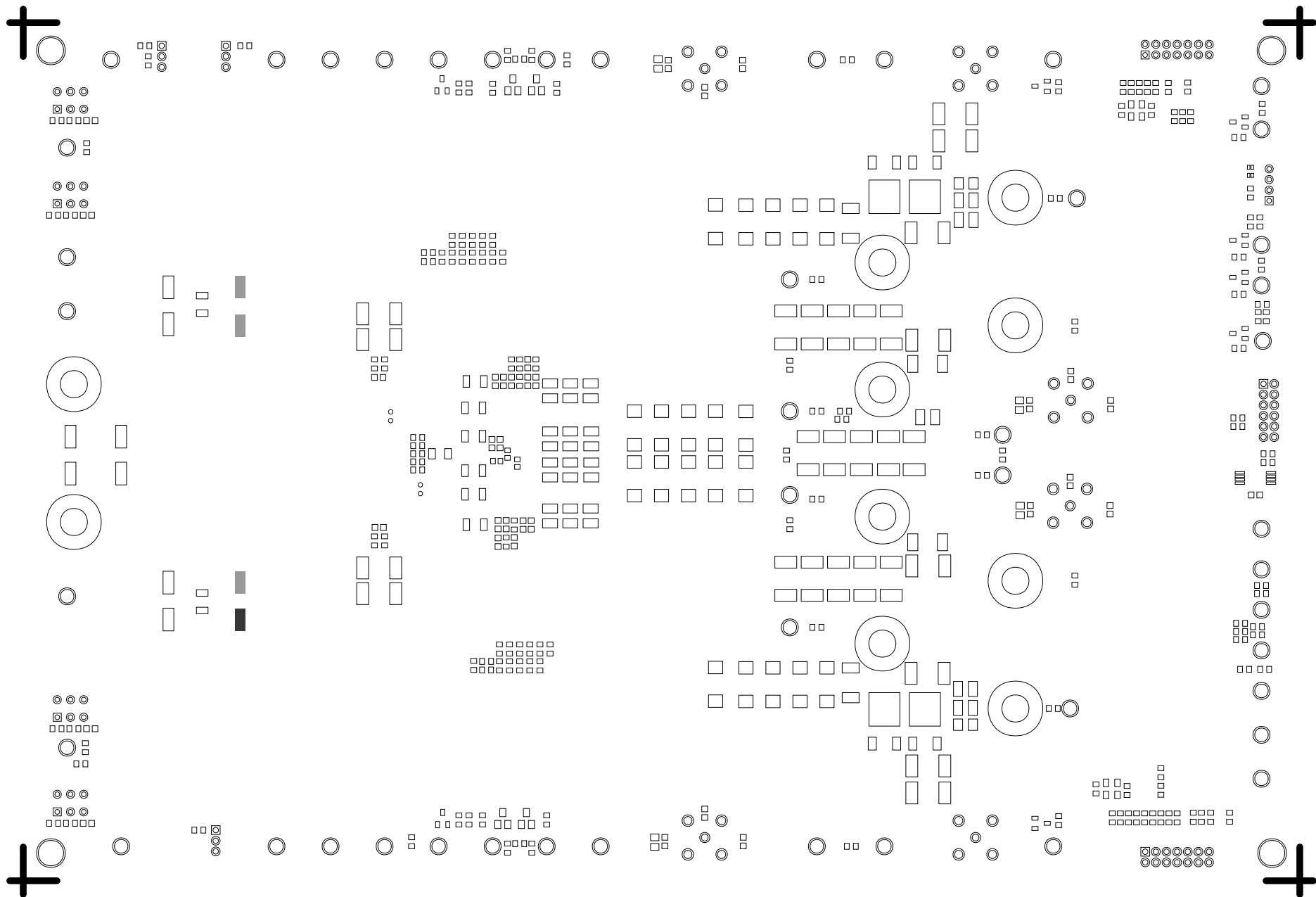
SOLDERMASK PRIMARY
08-070748-04
REV B



SOLDERMASK SECONDARY

08-070748-06

REV B



PASTEMASK PRIMARY
08-070748-13
REV B



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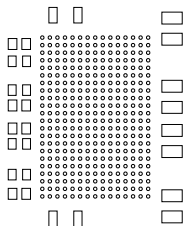
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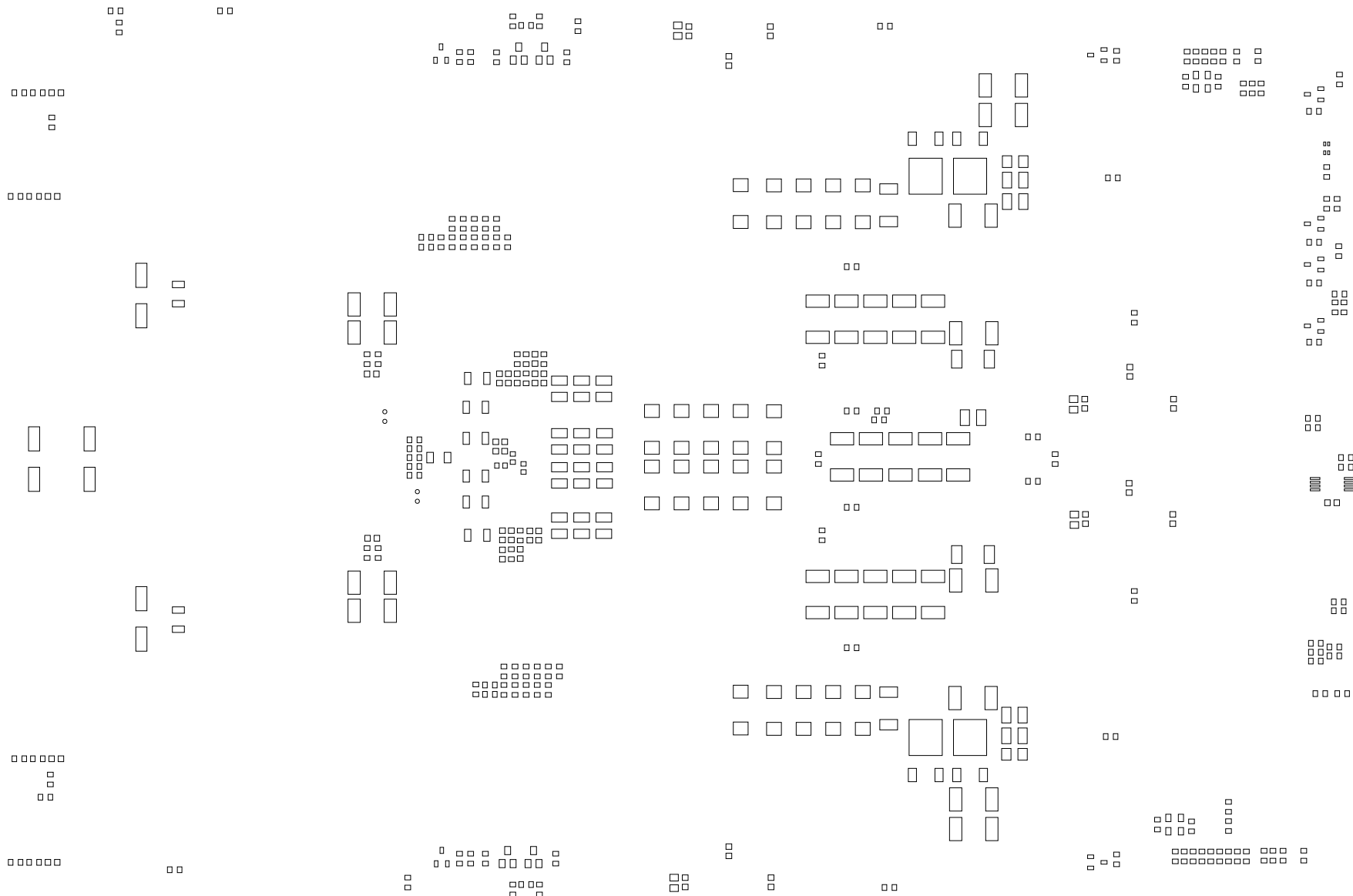
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□

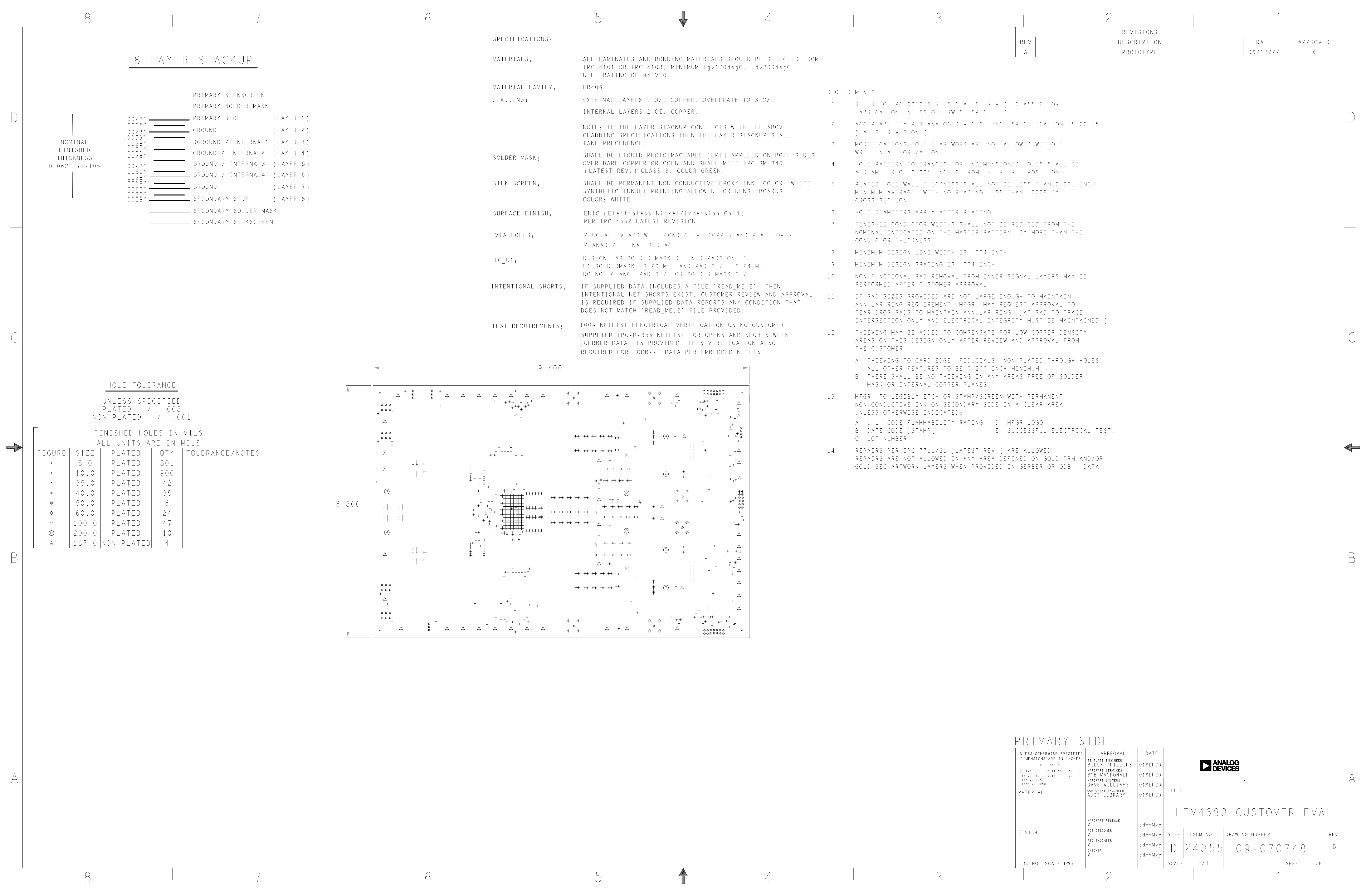


PASTEMASK SECONDARY

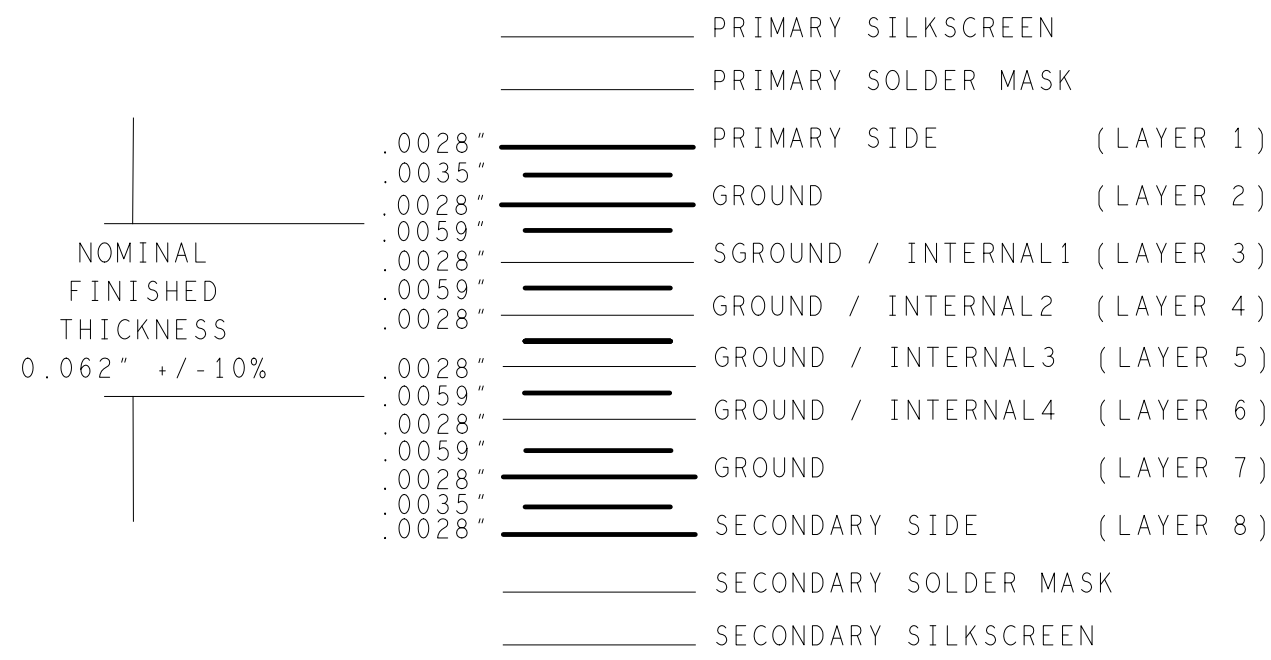
08-070748-14

REV B





8 LAYER STACKUP



HOLE TOLERANCE

UNLESS SPECIFIED
PLATED: +/- .003
NON PLATED: +/- .001

FINISHED HOLES IN MILS				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
+	8.0	PLATED	301	
+	10.0	PLATED	900	
•	35.0	PLATED	42	
•	40.0	PLATED	35	
•	50.0	PLATED	6	
•	60.0	PLATED	24	
Δ	100.0	PLATED	47	
⊙	200.0	PLATED	10	
A	187.0	NON-PLATED	4	

SPECIFICATIONS:

- MATERIALS; ALL LAMINATES AND BONDING MATERIALS SHOULD BE SELECTED FROM IPC-4101 OR IPC-4103, MINIMUM Tg>170degC, Td>300degC, U.L. RATING OF 94 V-0
- MATERIAL FAMILY; FR406
- CLADDING; EXTERNAL LAYERS 1 OZ. COPPER, OVERPLATE TO 3 OZ. INTERNAL LAYERS 2 OZ. COPPER.
- NOTE: IF THE LAYER STACKUP CONFLICTS WITH THE ABOVE CLADDING SPECIFICATIONS THEN THE LAYER STACKUP SHALL TAKE PRECEDENCE.
- SOLDER MASK; SHALL BE LIQUID PHOTOIMAGEABLE (LPI) APPLIED ON BOTH SIDES OVER BARE COPPER OR GOLD AND SHALL MEET IPC-SM-840 (LATEST REV.) CLASS 3. COLOR GREEN.
- SILK SCREEN; SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK. COLOR: WHITE SYNTHETIC INKJET PRINTING ALLOWED FOR DENSE BOARDS. COLOR: WHITE
- SURFACE FINISH; ENIG (Electroless Nickel/Immersion Gold) PER IPC-4552 LATEST REVISION
- VIA HOLES; PLUG ALL VIA'S WITH CONDUCTIVE COPPER AND PLATE OVER. PLANARIZE FINAL SURFACE.
- IC_U1; DESIGN HAS SOLDER MASK DEFINED PADS ON U1. U1 SOLDERMASK IS 20 MIL AND PAD SIZE IS 24 MIL. DO NOT CHANGE PAD SIZE OR SOLDER MASK SIZE.
- INTENTIONAL SHORTS; IF SUPPLIED DATA INCLUDES A FILE "READ_ME.2", THEN INTENTIONAL NET SHORTS EXIST. CUSTOMER REVIEW AND APPROVAL IS REQUIRED IF SUPPLIED DATA REPORTS ANY CONDITION THAT DOES NOT MATCH "READ_ME.2" FILE PROVIDED.
- TEST REQUIREMENTS; 100% NETLIST ELECTRICAL VERIFICATION USING CUSTOMER SUPPLIED IPC-D-356 NETLIST FOR OPENS AND SHORTS WHEN "GERBER DATA" IS PROVIDED. THIS VERIFICATION ALSO REQUIRED FOR "ODB++" DATA PER EMBEDDED NETLIST.

REQUIREMENTS:

- REFER TO IPC-6010 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
- ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00115, (LATEST REVISION.)
- MODIFICATIONS TO THE ARTWORK ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
- HOLE PATTERN TOLERANCES FOR UNDIMENSIONED HOLES SHALL BE A DIAMETER OF 0.005 INCHES FROM THEIR TRUE POSITION.
- PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN 0.001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY CROSS SECTION.
- HOLE DIAMETERS APPLY AFTER PLATING.
- FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
- MINIMUM DESIGN LINE WIDTH IS .004 INCH.
- MINIMUM DESIGN SPACING IS .004 INCH.
- NON-FUNCTIONAL PAD REMOVAL FROM INNER SIGNAL LAYERS MAY BE PERFORMED AFTER CUSTOMER APPROVAL.
- IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNULAR RING REQUIREMENT, MFR. MAY REQUEST APPROVAL TO TEAR DROP PADS TO MAINTAIN ANNULAR RING. (AT PAD TO TRACE INTERSECTION ONLY AND ELECTRICAL INTEGRITY MUST BE MAINTAINED.)
- THIEVING MAY BE ADDED TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN ONLY AFTER REVIEW AND APPROVAL FROM THE CUSTOMER:
 - A. THIEVING TO CARD EDGE, FIDUCIALS, NON-PLATED THROUGH HOLES, ALL OTHER FEATURES TO BE 0.200 INCH MINIMUM.
 - B. THERE SHALL BE NO THIEVING IN ANY AREAS FREE OF SOLDER MASK OR INTERNAL COPPER PLANES.
- MFR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED;
 - A. U.L. CODE-FLAMMABILITY RATING
 - B. DATE CODE (STAMP).
 - C. LOT NUMBER
 - D. MFR LOGO
 - E. SUCCESSFUL ELECTRICAL TEST.
- REPAIRS PER IPC-7711/21 (LATEST REV.) ARE ALLOWED. REPAIRS ARE NOT ALLOWED IN ANY AREA DEFINED ON GOLD_PRM AND/OR GOLD_SEC ARTWORK LAYERS WHEN PROVIDED IN GERBER OR ODB++ DATA.

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS FRACTIONS ANGLES .XX .-. .010 .-./32 .-. 2 .XXX .-. .005 .XXXX .-. .0050	APPROVAL	DATE				
	TEMPLATE ENGINEER BILLY PHILLIPS	01SEP20				
	HARDWARE SERVICES BOB MACDONALD	01SEP20				
	HARDWARE SYSTEMS DAVE WILLIAMS	01SEP20				
MATERIAL	COMPONENT ENGINEER ADGT LIBRARY	01SEP20	TITLE			
			LTM4683 CUSTOMER EVAL			
FINISH	PCB DESIGNER X	ddMMyy	SIZE	FSCM NO	DRAWING NUMBER	REV
	PID ENGINEER X	ddMMyy	D	24355	09-070748	B
	CHECKER X	ddMMyy				
	DO NOT SCALE DWG		SCALE	1/1	SHEET	OF